

## **AMENDMENTS TO THE SPECIFICATION**

Please amend the title to read:

--MEMS PACKAGE--.

Please add the following paragraph before the first paragraph on page 1:

--Cross Reference to Related Application

This application is a divisional of co-pending U.S. Patent Application No. 10/057,368, filed January 25, 2001 and entitled A WAFER-LEVEL THROUGH-WAFER PACKAGING PROCESS FOR MEMS AND MEMS PACKAGE PRODUCED THEREBY, the disclosure of which is incorporated herein by reference in its entirety as if completely set forth herein below.--